



## Material Content Data Sheet



<b>Sales Product Name</b>		IPB50N10S3L-16		<b>Issued</b>		20. July 2018		
<b>MA#</b>		MA001656892						
<b>Package</b>		PG-TO263-3-2		<b>Weight*</b>		1559.81 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.497	0.29	0.29	2883	2883
leadframe	inorganic material	phosphorus	7723-14-0	0.091	0.01		59	
	non noble metal	iron	7439-89-6	0.304	0.02		195	
	non noble metal	copper	7440-50-8	304.026	19.49	19.52	194913	195167
	non noble metal	aluminium	7429-90-5	5.686	0.36	0.36	3645	3645
wire	non noble metal	aluminium	7429-90-5	5.686	0.36	0.36	3645	3645
encapsulation	organic material	carbon black	1333-86-4	10.244	0.66		6567	
	plastics	epoxy resin	-	112.679	7.22		72239	
	inorganic material	silicondioxide	60676-86-0	559.979	35.89	43.77	359005	437811
leadfinish	non noble metal	tin	7440-31-5	9.657	0.62	0.62	6191	6191
plating	inorganic material	phosphorus	7723-14-0	0.001	0.00		1	
	non noble metal	nickel	7440-02-0	0.228	0.01	0.01	146	147
solder	non noble metal	tin	7440-31-5	0.081	0.01		52	
	noble metal	silver	7440-22-4	0.101	0.01		65	
	non noble metal	lead	7439-92-1	3.854	0.25	0.27	2471	2588
heatspreader	inorganic material	phosphorus	7723-14-0	0.165	0.01		105	
	non noble metal	iron	7439-89-6	0.548	0.04		352	
	non noble metal	copper	7440-50-8	547.666	35.11	35.16	351111	351568
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com